

SOT1426-1

plastic thermal enhanced ultra thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.56 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HUQFN32
Package type industry code	HUQFN32
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-8-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	0.45	-	0.56	0.6	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	32	-	

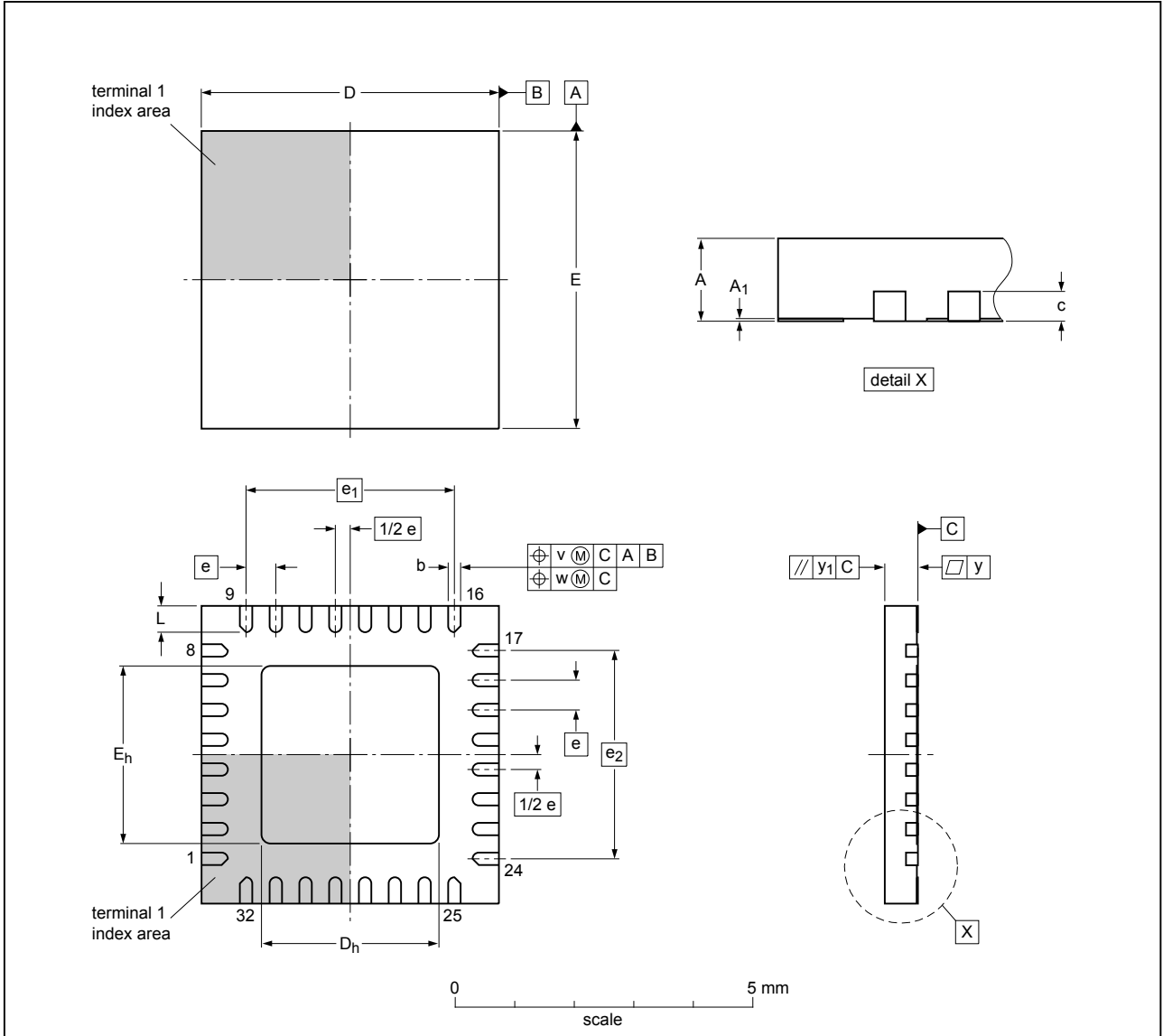


plastic thermal enhanced ultra thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.56 mm

2. Package outline

HUQFN32: plastic thermal enhanced ultra thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.56 mm

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Dimensions (mm are the original dimensions)

Unit	A ⁽¹⁾	A ₁	b	C	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	0.60	0.05	0.30		5.1	3.1	5.1	3.1				0.45				
nom	0.56	0.02	0.21	0.2	5.0	3.0	5.0	3.0	0.5	3.5	3.5	0.40	0.1	0.05	0.05	0.1
min	0.45	0.00	0.18		4.9	2.9	4.9	2.9				0.35				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1426-1					14-08-06 14-08-07

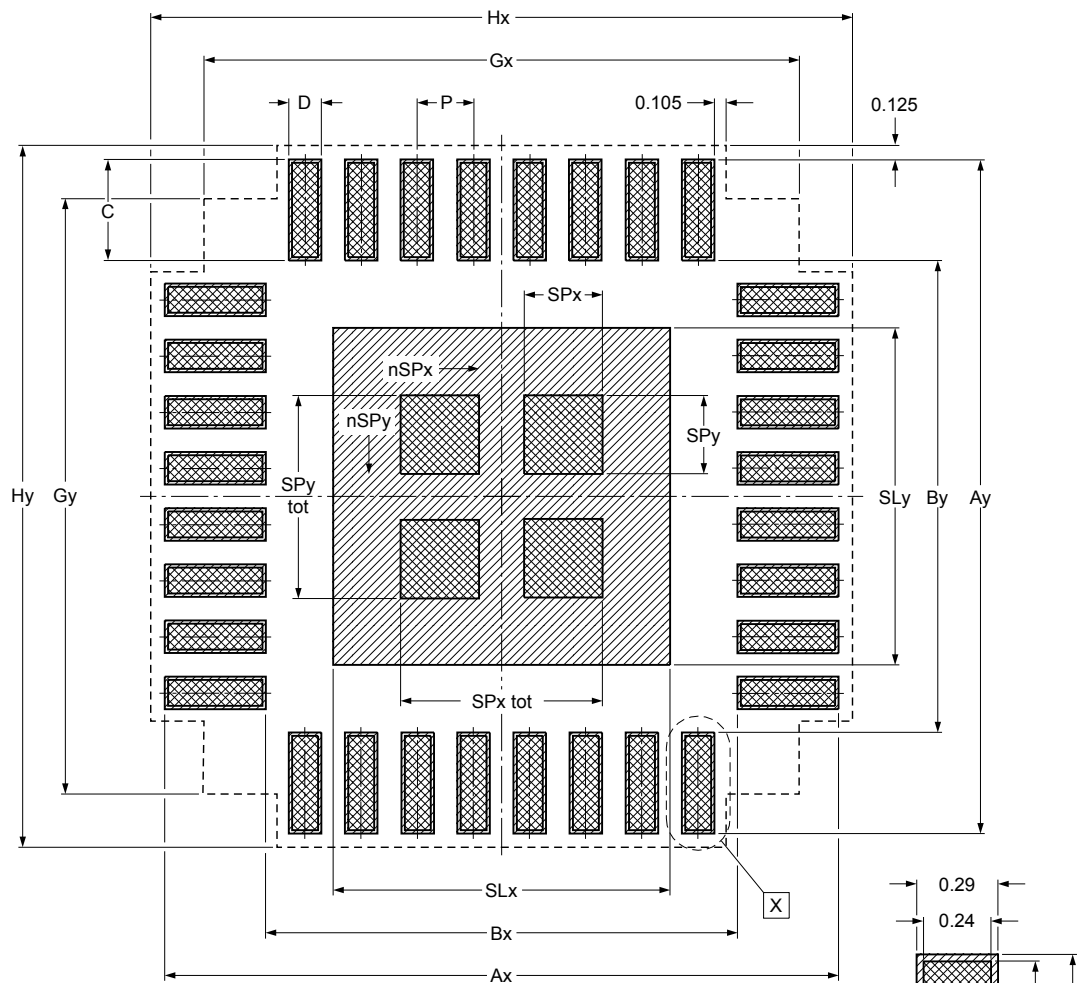
Fig. 1. Package outline HUQFN32 (SOT1426-1)

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3. Soldering

Footprint information for reflow soldering of HUQFN32 package

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- solder land
- solder land plus solder paste
- solder paste deposit
- occupied area

Dimensions in mm Recommended stencil thickness: 0.1 mm

P	Ax	Ay	Bx	By	SLx	SLy	SPx	SPy	SPx tot	SPy tot	C	D	nSPx	nSPy	Gx	Gy	Hx	Hy
0.5	6.0	6.0	4.2	4.2	3.0	3.0	0.7	0.7	1.8	1.8	0.9	0.29	2	2	5.3	5.3	6.25	6.25

Issue date ~~15-06-30~~
15-07-21

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Fig. 2. Reflow soldering footprint for HUQFN32 (SOT1426-1)

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4. Legal information

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